





# PRODUCT SPECIFICATION

## 5.0 PERFORMANCE

### 5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
1	<b>Insulation Resistance</b>	Measurements taken between adjacent contacts where 500VDC is applied. (MIL-STD-202F, Method 302)	<b>12000</b> Megaohms Minimum
2	<b>Dielectric Strength</b>	Mated samples subjected to 900 VAC rms for 1 min. between adjacent contacts. (MIL-STD-202F, Method 301)	No breakdown
3	<b>Current Rating</b>	Steady state DC voltage source is supplied for 96 hours with a 30 degree C Max. temperature rise over ambient	2.5 amp (D.C.) Maximum

### 5.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
4	<b>Contact Retention</b>	Apply axial load at a rate of 0.5 inch/ (12.7mm) minimum up to maximum required load. (MIL-STD-1344A, Method 2007.1)	2 lb / 0.91kgf (Minimum) Initial 0.88 lb / 0.40kgf (Minimum) After resistance to solder heat

REVISION:	ECR/ECN INFORMATION:	TITLE:	SHEET No.
<b>H2</b>	EC No: <b>S2006-0380</b> DATE: <b>2005/09/23</b>	<b>C-GRID SHROUDED WAFER</b>	<b>2 of 3</b>
DOCUMENT NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPROVED BY:
<b>PS-70246-100</b>	<b>YLQIAO 2005/09/23</b>	<b>BOKOK 2005/09/27</b>	<b>PTLIM 2005/09/27</b>



# PRODUCT SPECIFICATION

## 5.3 ENVIRONMENTAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5	<b>Resistance to Soldering Heat (Wave Soldering)</b> For Series: 87256, 87257, 87834, 87835, 70246, 70247 87556	Sample mounted on PCB and subject to wave soldering as per MIL-STD-202G, method 210F, Condition B  For series using a) Nylon 4/6 plastic material Temperature : 260 ±5°C for 5sec b) PBT / PET plastic material Temperature : 230 ±5°C for 3sec	No damage in appearance of the connector
6	<b>Resistance to Soldering Heat (Reflow)</b> For Series: 71384, 87054	1. <u>Preheat</u> : Increase in temperature < 4°C /sec 2. <u>Soldering</u> : Maximum Reflow temperature < 230°C 3. <u>Cool Down</u> : Cool temperature < 4°C /sec	No damage in appearance of the connector
7	<b>Solderability</b>	Solder tail to be dipped in flux as per MIL-STD-202F, method 208	Soldertail should have 95% continuous new solder coating coverage (Apply to non-kinked Soldertail only)

## 6.0 PACKAGING

Product shall be packaged and protected against damage during handling, transportation and storage.

REVISION: <b>H2</b>	ECR/ECN INFORMATION: EC No: <b>S2006-0380</b> DATE: <b>2005/09/23</b>	TITLE: <b>C-GRID SHROUDED WAFER</b>	SHEET No. <b>3 of 3</b>
DOCUMENT NUMBER: <b>PS-70246-100</b>	CREATED / REVISED BY: <b>YLQIAO 2005/09/23</b>	CHECKED BY: <b>BOKOK 2005/09/27</b>	APPROVED BY: <b>PTLIM 2005/09/27</b>